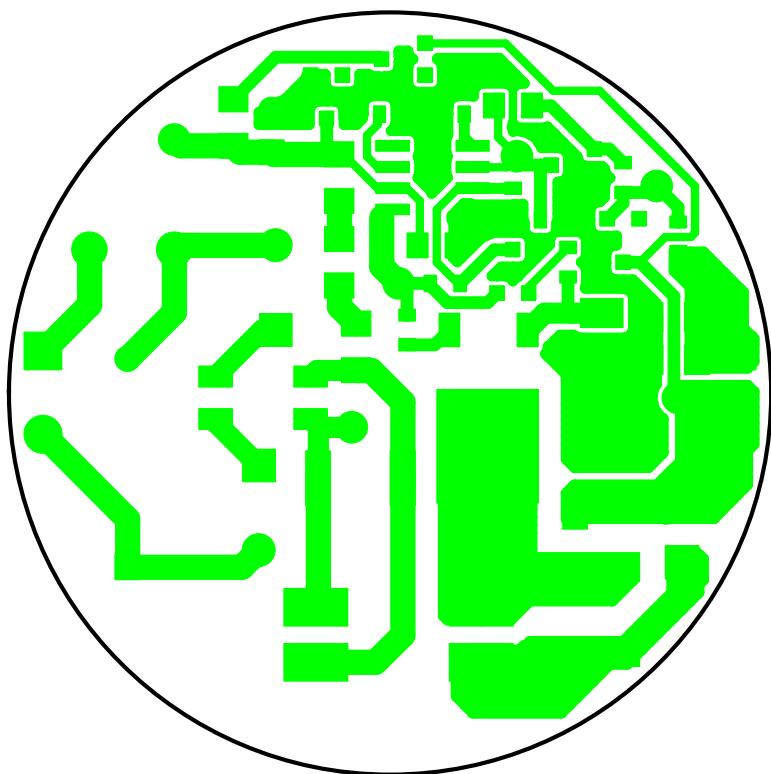
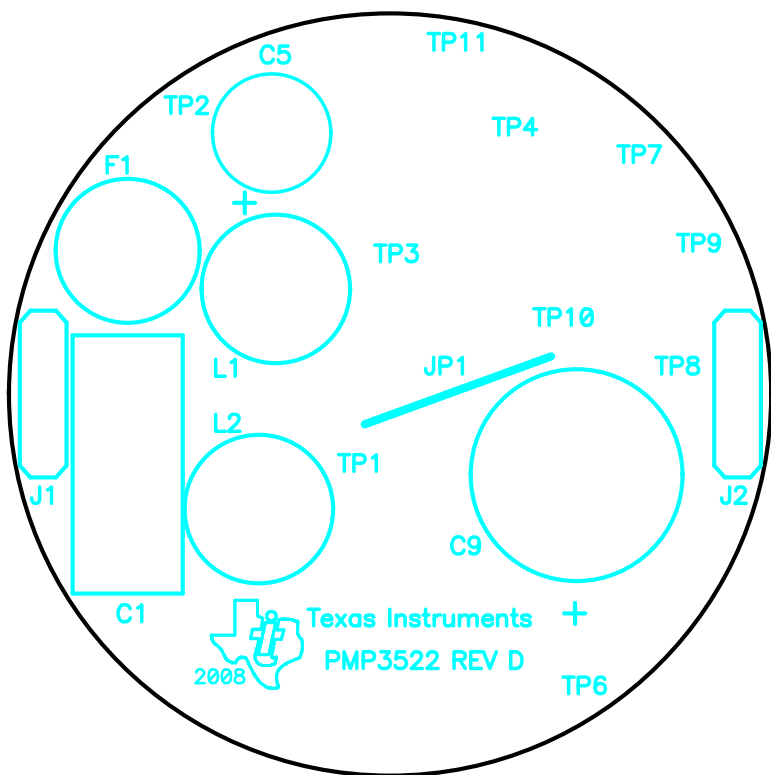
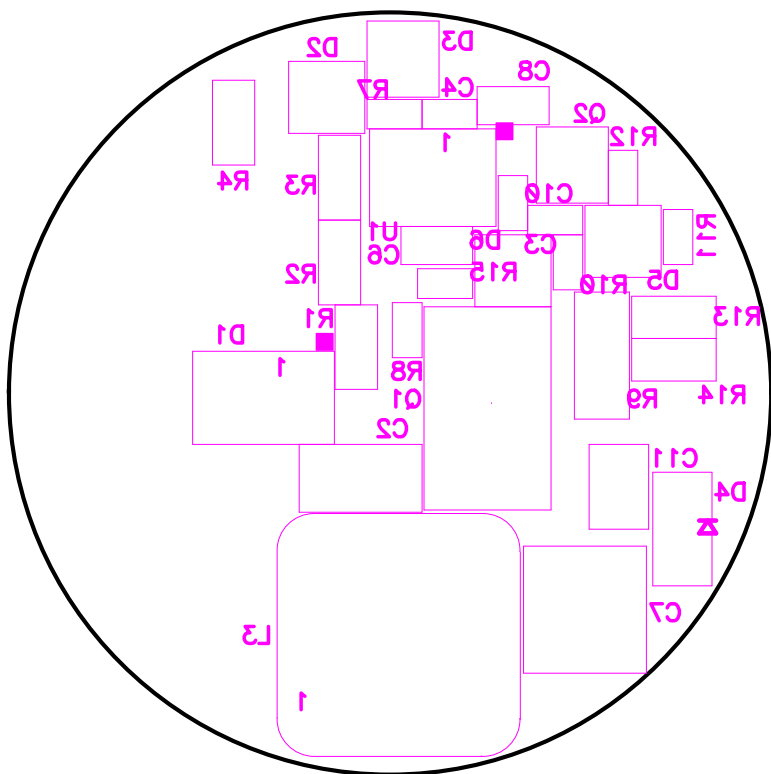




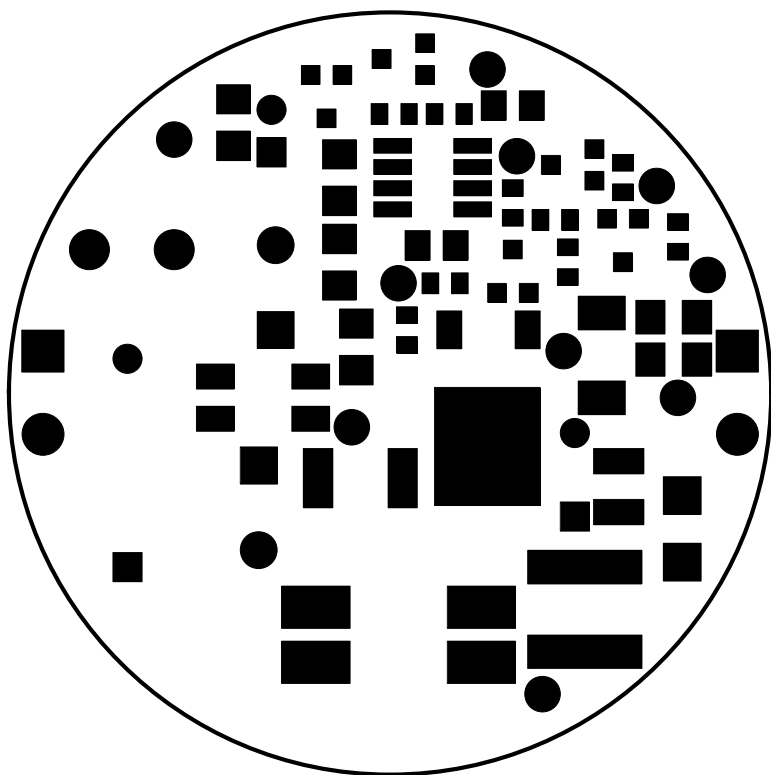
TEXAS INSTRUMENTS		Copper		Silkscreen		S Mask		Assembly		Fab Drawing
		Bottom		Top	Bot	Bottom		Top	Bot	
Board No. PMP 3522		Rev. D		BC						
Date: 10-03-2008	Filename: PMP3522_REVD.pcb	Engineer: Salil Chellappan		PCB Dsgnr: Salil C		Modified Date: Thu Oct 07, 2010			Time Stamp: 15:03:06	



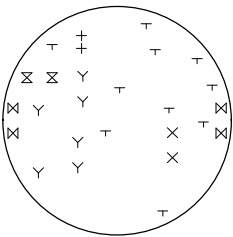
TEXAS INSTRUMENTS		Copper		Silkscreen		S Mask		Assembly		Fab Drawing
		Bottom		Top	Bot	Bottom		Top	Bot	
Board No. PMP 3522		Rev. D			TS					
Date: 10-03-2008	Filename: PMP3522_REVD.pcb	Engineer: Salil Chellappan		PCB Dsgnr: Salil C		Modified Date: Thu Oct 07, 2010			Time Stamp: 15:03:06	



TEXAS INSTRUMENTS		Copper		Silkscreen		S Mask		Assembly		Fab Drawing
		Bottom		Top	Bot	Bottom		Top	Bot	
Board No. PMP 3522		Rev. D			BS					
Date: 10-03-2008	Filename: PMP3522_REVD.pcb	Engineer: Salil Chellappan		PCB Dsgnr: Salil C		Modified Date: Thu Oct 07, 2010		Time Stamp: 15:03:06		



TEXAS INSTRUMENTS		Copper		Silkscreen		S Mask	Assembly		Fab Drawing
		Bottom		Top	Bot	Bottom	Top	Bot	
Board No. PMP 3522		Rev. D					BM		
Date: 10-03-2008	Filename: PMP3522_REVD.pcb	Engineer: Salil Chellappan		PCB Dsgnr: Salil C		Modified Date: Thu Oct 07, 2010		Time Stamp: 15:03:07	



TEXAS INSTRUMENTS				Copper		Silkscreen		S Mask		Assembly		Fab Drawing
Board No.		Rev.		Bottom	Top	Bot	Bottom	Top	Bot	Top	Bot	
PMP 3522		D										FB
Date: 10-03-2008		Filename: PMP3522_REV D.pcb		Engineer: Sathil Chellappan		PCB Design: Sathil C		Modified Date: Thu Oct 07, 2010		Time Stamp: 15:03:07		

FABRICATION CHART			
FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT
☐ 0.031 ☒ 0.062 ☐ 0.093 ☐ 0.125	☒ LAYER 1 ☒ LAYER 2 ☐ NONE	☒ LAYER 1 ☐ LAYER 2 ☐ NONE	☐ 1 OZ. ☒ 2 OZ. ☐ OTHER _____
DESIGN	TRACE/GAP SPACING		LAYER COUNT
☐ SMD ☐ THRU-HOLE ☒ MIX	☒ 0.010/0.010 ☐ 0.008/0.007 ☐ 0.006/0.006		☒ SINGLE SIDED ☐ 2 LAYER ☐ 4 LAYER ☐ OTHER _____

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL:

ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.
2. BASE LAMINATE:

PLASTIC SHEET, LAMINATED METAL CLAD, TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 2 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
3. SOLDERMASK:

SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840.
4. PLATING:

NO PLATING IN HOLES REQUIRED.
5. FINISH:

PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0005" +/- 0.0003" THICK MIN ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
6. LEGEND:

IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
7. MARKINGS:

BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
8. WORKMANSHIP:

BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
9. DOCUMENTATION:

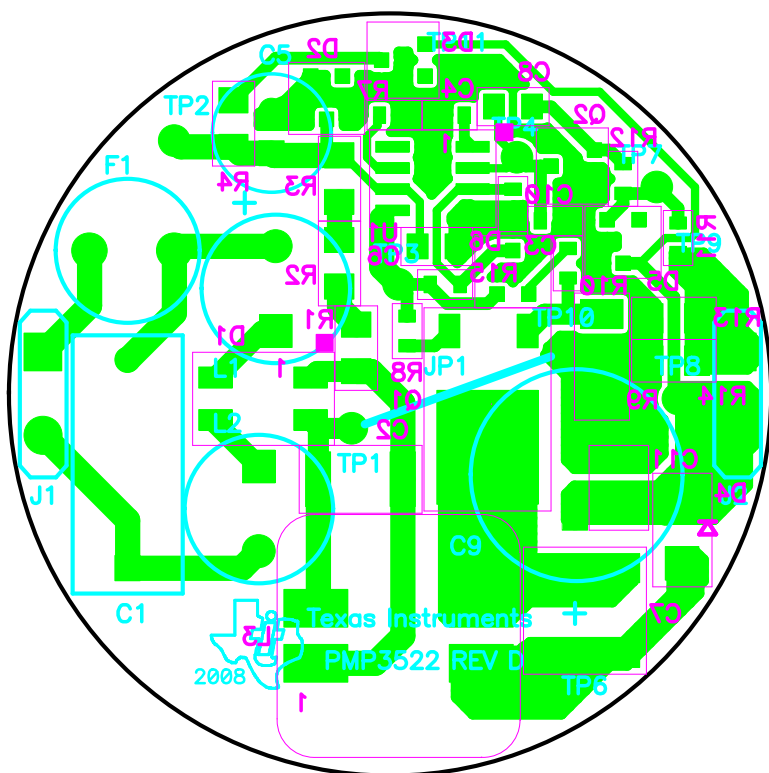
PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
10. DRILL SIZES:

HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
11. PANEL BORDER:

ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
12. PROCESS CHANGES:

NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.

Drill Table			
Hole Dia (inch)	Symbol	Quantity	Plated
0.032	+	2	Yes
0.035	X	2	Yes
0.038	Y	6	Yes
0.040	T	10	Yes
0.051	X	2	Yes
0.062	M	4	Yes



TEXAS INSTRUMENTS		Copper		Silkscreen		S Mask		Assembly		Fab Drawing
		Bottom		Top	Bot	Bottom		Top	Bot	
Board No.	PMP 3522	Rev.		D	BC	TS	BS			
Date:	10-03-2008	Filename:		PMP3522_REVD.pcb	Engineer:		Salil Chellappan	PCB Dsgnr:		Salil C
Modified Date:		Thu Oct 07, 2010		Time Stamp:		15:03:07				

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